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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









IGBT

SGR2N60UF

Ultra-Fast IGBT

General Description

Fairchild's UF series of Insulated Gate Bipolar Transistors (IGBTs) provides low conduction and switching losses. The UF series is designed for applications such as motor control and general inverters where high speed switching is a required feature.

Features

- · High speed switching
- Low saturation voltage : $V_{CE(sat)} = 2.1 \text{ V } @ I_C = 1.2 \text{A}$
- · High input impedance

Applications

AC & DC motor controls, general purpose inverters, robotics, and servo controls.





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Description		SGR2N60UF	Units
V _{CES}	Collector-Emitter Voltage		600	V
V _{GES}	Gate-Emitter Voltage		± 20	V
I _C	Collector Current	@ T _C = 25°C	2.4	Α
	Collector Current	@ T _C = 100°C	1.2	Α
I _{CM (1)}	Pulsed Collector Current		10	Α
P _D	Maximum Power Dissipation	@ T _C = 25°C	25	W
	Maximum Power Dissipation	@ T _C = 100°C	10	W
T _J	Operating Junction Temperature		-55 to +150	°C
T _{stg}	Storage Temperature Range		-55 to +150	°C
T _L	Maximum Lead Temp. for Soldering Purposes, 1/8" from Case for 5 Seconds		300	°C

(1) Repetitive rating : Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		5.0	°C/W
$R_{ heta JA}$	Thermal Resistance, Junction-to-Ambient (PCB Mount) (2)	-	50	°C/W

Notes:
(2) Mounted on 1" squre PCB (FR4 or G-10 Material)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Cha	racteristics					
BV _{CES}	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V, I_{C} = 250uA$	600			V
$\Delta B_{VCES}/$ ΔT_J	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0V$, $I_C = 1mA$		0.6		V/°C
I _{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$			250	uA
I _{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$			± 100	nA
On Cha	racteristics					
V _{GE(th)}	G-E Threshold Voltage	$I_C = 1.2 \text{mA}, V_{CE} = V_{GE}$	3.5	4.5	6.5	V
	Collector to Emitter	$I_C = 1.2A$, $V_{GE} = 15V$		2.1	2.6	٧
V _{CE(sat)}	Saturation Voltage	I _C = 2.4A, V _{GE} = 15V		2.6		V
Dynami	c Characteristics					
C _{ies}	Input Capacitance	V 30V V 0V		98		pF
C _{oes}	Output Capacitance	V _{CE} = 30V _, V _{GE} = 0V, f = 1MHz		18		pF
C _{res}	Reverse Transfer Capacitance	- 1 - 11VII 12		4		pF
	ng Characteristics Turn-On Delay Time	T		15		
t _{d(on)}	Rise Time	-		20		ns ns
t _r	Turn-Off Delay Time	V 200 V I 12A		80	130	ns
t _{d(off)} t _f	Fall Time	$V_{CC} = 300 \text{ V}, I_{C} = 1.2\text{A},$ $R_{G} = 200\Omega, V_{GE} = 15\text{V},$		95	160	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 25°C		30		uJ
E _{off}	Turn-Off Switching Loss			13		uJ
E _{ts}	Total Switching Loss			43	70	uJ
				19		
	Turn-On Delay Time			1 19		ns
t _{d(on)}	Turn-On Delay Time Rise Time			24		ns ns
t _{d(on)} t _r	•	V _{CC} = 300 V. I _C = 1.2A.		-		
t _{d(on)} t _r t _{d(off)}	Rise Time	$V_{CC} = 300 \text{ V}, I_{C} = 1.2\text{A},$ $R_{G} = 200\Omega, V_{GE} = 15\text{V},$		24		ns
t _{d(on)} t _r t _{d(off)} t _f	Rise Time Turn-Off Delay Time	V_{CC} = 300 V, I_{C} = 1.2A, R_{G} = 200 Ω , V_{GE} = 15V, Inductive Load, T_{C} = 125°C		24 115	200	ns ns
$t_{d(on)}$ t_r $t_{d(off)}$ t_f E_{on}	Rise Time Turn-Off Delay Time Fall Time	$R_G = 200\Omega$, $V_{GE} = 15V$,		24 115 176	200 250	ns ns ns
t _{d(on)} t _r t _{d(off)} t _f E _{on}	Rise Time Turn-Off Delay Time Fall Time Turn-On Switching Loss	$R_G = 200\Omega$, $V_{GE} = 15V$,	 	24 115 176 36	200 250	ns ns ns uJ
t _{d(on)} t _r t _{d(off)} t _f E _{on} E _{off} E _{ts}	Rise Time Turn-Off Delay Time Fall Time Turn-On Switching Loss Turn-Off Switching Loss	$R_G = 200\Omega$, $V_{GE} = 15V$, Inductive Load, $T_C = 125^{\circ}C$	 	24 115 176 36 27	200 250 	ns ns ns uJ uJ
$\begin{array}{c} t_{d(on)} \\ t_r \\ \end{array}$ $\begin{array}{c} t_{d(off)} \\ t_f \\ E_{on} \\ E_{off} \\ E_{ts} \\ Q_g \end{array}$	Rise Time Turn-Off Delay Time Fall Time Turn-On Switching Loss Turn-Off Switching Loss Total Switching Loss	$R_G = 200\Omega$, $V_{GE} = 15V$, Inductive Load, $T_C = 125^{\circ}C$ $V_{CE} = 300 \text{ V}, I_C = 1.2A,$	 	24 115 176 36 27 63	200 250 100	ns ns ns uJ uJ
t _d (on) t _r t _{d(off)} t _f E _{on} E _{off} E _{ts} Q _g Q _{ge} Q _{gc}	Rise Time Turn-Off Delay Time Fall Time Turn-On Switching Loss Turn-Off Switching Loss Total Switching Loss Total Gate Charge	$R_G = 200\Omega$, $V_{GE} = 15V$, Inductive Load, $T_C = 125^{\circ}C$	 	24 115 176 36 27 63 9	200 250 100 14	ns ns ns uJ uJ uJ

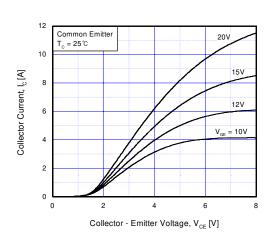


Fig 1. Typical Output Characteristics

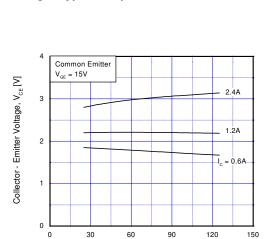


Fig 3. Saturation Voltage vs. Case Temperature at Variant Current Level

Case Temperature, T_c [$^{\circ}$ C]

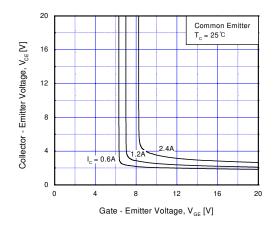


Fig 5. Saturation Voltage vs. V_{GE}

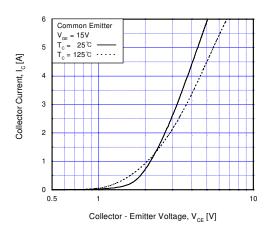


Fig 2. Typical Saturation Voltage Characteristics

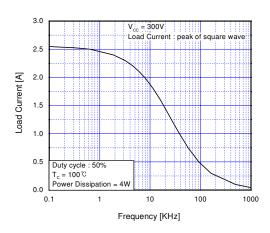


Fig 4. Load Current vs. Frequency

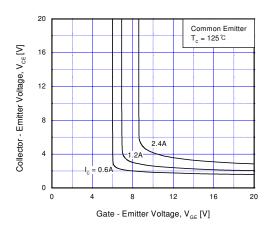
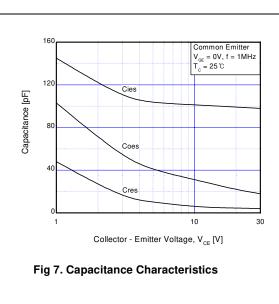


Fig 6. Saturation Voltage vs. V_{GE}



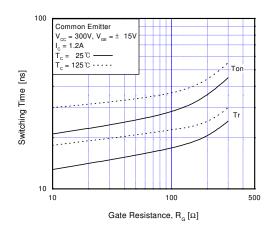
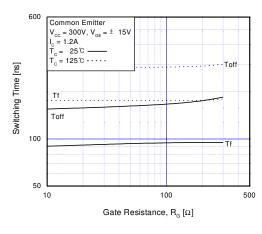


Fig 8. Turn-On Characteristics vs.
Gate Resistance



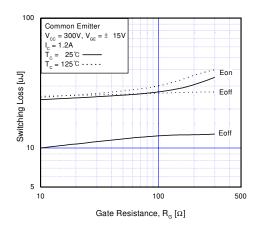
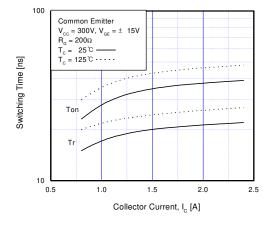


Fig 9. Turn-Off Characteristics vs.
Gate Resistance

Fig 10. Switching Loss vs. Gate Resistance



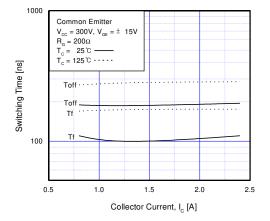
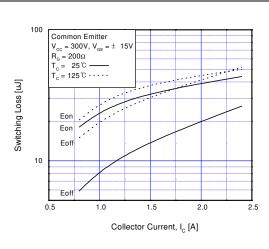


Fig 11. Turn-On Characteristics vs. Collector Current

Fig 12. Turn-Off Characteristics vs. Collector Current



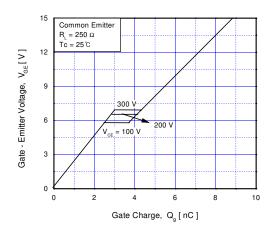
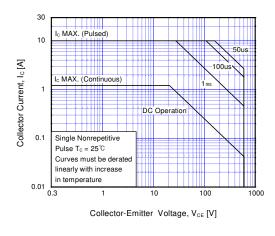


Fig 13. Switching Loss vs. Collector Current

Fig 14. Gate Charge Characteristics



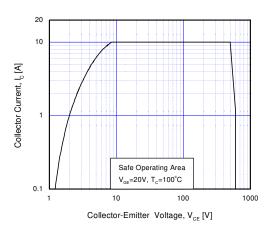


Fig 15. SOA Characteristics

Fig 16. Turn-Off SOA Characteristics

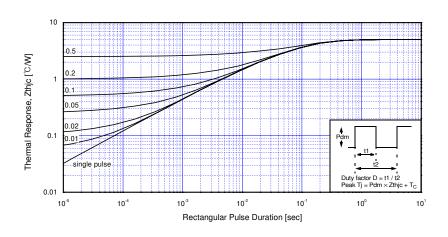
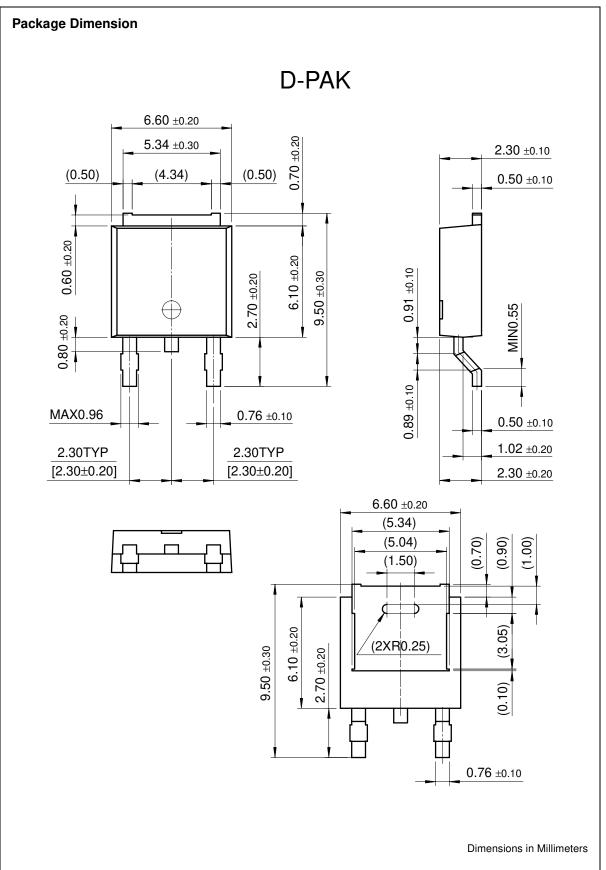


Fig 17. Transient Thermal Impedance of IGBT



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